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PRODUCT INFORMATION NOTIFICATION

PIN: PIN194401

Date: October 29, 2019

Subject: Standardize HBM, CDM and MM ESD Specification in the Datasheet for Select F-RAM Devices

Change Type: Minor

Description of Change:

Cypress announces HBM, CDM and MM ESD specification changes in the datasheets for 4Kb 2.7-3.6V SPI F-RAM and 4Kb 4.5-5.5V SPI F-RAM. The HBM specification is changed from 4000V to 2000V, the CDM specification is changed from 1250V to 500V and MM spec is removed in the datasheets. The purpose of this change is to standardize HBM, CDM and MM ESD specification to JEDEC standard limits used for qualifying Cypress devices. There is no change to silicon design, test methodology or manufacturing sites, and hence we expect end applications to be unaffected.

The updated product datasheet is attached to this notification.

Part Numbers Affected: 4

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change.

Approximate Implementation Date:

This change will be effective with the date of this notification.

Anticipated Impact:

There is no change to the product. Products manufactured with revised datasheet parameter are completely compatible with existing product from fit, form, functional, parametric, and quality performance perspectives.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

This is an information only announcement. No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Item Marketing Part Number

- 1 CY15B004Q-SXA
- 2 CY15B004Q-SXAT
- 3 CY15E004Q-SXA
- 4 CY15E004Q-SXAT